

# 1.2V Drive Nch MOSFET

#### **RUE002N05**

#### Structure

Silicon N-channel MOSFET

#### Features

- 1) High speed switing.
- 2) Small package(EMT3).
- 3)Ultra low voltage drive(1.2V drive).

#### Application

Switching

Packaging specifications

	Package	Taping	
Type	Code	TL	
	Basic ordering unit (pieces)	3000	
RUE002N05		0	

● Absolute maximum ratings (Ta = 25°C)

Parame	Symbol	Limits	Unit	
Drain-source voltage	V <sub>DSS</sub>	50	V	
Gate-source voltage	$V_{GSS}$	±8	V	
Drain current	Continuous		±200	mA
Diam current	Pulsed	I <sub>DP</sub> *1	±800	mΑ
Source current	Continuous	Is	125	mA
(Body Diode)	Pulsed	I <sub>SP</sub> *1	800	mA
Power dissipation		P <sub>D</sub> *2	150	mW
Channel temperature	Tch	150	°C	
Range of storage temperature		Tstg	-55 to +150	°C

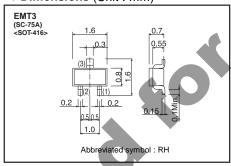
<sup>\*1</sup> Pw≤10µs, Duty cycle≤1%

#### Thermal resistance

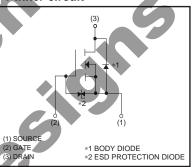
Parameter	Symbol	Limits	Unit
Channel to ambient	Rth (ch-a)*	833	°C/W

<sup>\*</sup> Each terminal mounted on a recommended land.

#### • Dimensions (Unit : mm)



#### • Inner circuit



<sup>\*2</sup> Each terminal mounted on a recommended land.

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#### ●Electrical characteristics (Ta = 25°C)

Parameter	Symbol	Min.	Тур.	Max.	Unit	Conditions
Gate-source leakage	$I_{GSS}$	1	-	±10	μA	$V_{GS}=\pm 8V, V_{DS}=0V$
Drain-source breakdown voltage	$V_{(BR)DSS}$	50	-	-	V	I <sub>D</sub> =1mA, V <sub>GS</sub> =0V
Zero gate voltage drain current	I <sub>DSS</sub>	1	-	1	μA	$V_{DS}$ =50V, $V_{GS}$ =0V
Gate threshold voltage	V <sub>GS (th)</sub>	0.3	-	1.0	V	$V_{DS}=10V$ , $I_{D}=1mA$
		1	1.6	2.2		I <sub>D</sub> =200mA, V <sub>GS</sub> =4.5V
Static ducin course on state		1	1.7	2.4		I <sub>D</sub> =200mA, V <sub>GS</sub> =2.5V
Static drain-source on-state resistance	R <sub>DS (on)</sub> *	1	1.9	2.7	Ω	I <sub>D</sub> =100mA, V <sub>GS</sub> =1.8V
- Colorano		1	2.0	4.0		I <sub>D</sub> =40mA, V <sub>GS</sub> =1.5V
		1	2.4	7.2		I <sub>D</sub> =20mA, V <sub>GS</sub> =1.2V
Forward transfer admittance	I Y <sub>fs</sub> I*	0.4	-	-	S	I <sub>D</sub> =200mA, V <sub>DS</sub> =10V
Input capacitance	C <sub>iss</sub>	1	25	-	pF	V <sub>DS</sub> =10V
Output capacitance	C <sub>oss</sub>	1	6	-	pF	V <sub>GS</sub> =0V
Reverse transfer capacitance	C <sub>rss</sub>	-	3	-	pF	f=1MHz
Turn-on delay time	t <sub>d(on)</sub> *	-	4	-	ns	$I_D=100$ mA, $V_{DD}=30$ V
Rise time	t <sub>r</sub> *	-	6	-	ns	V <sub>GS</sub> =4.5V
Turn-off delay time	t <sub>d(off)</sub> *	-	15	-	ns	R <sub>L</sub> =300Ω
Fall time	t <sub>f</sub> *	-	55	-	ns	R <sub>G</sub> =10Ω

<sup>\*</sup>Pulsed

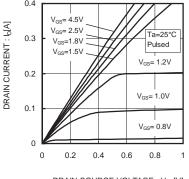
●Body diode characteristics (Source-Drain) (Ta = 25°C)

Parameter	Symbol	Min.	Тур.	Max.	Unit	Conditions
Forward voltage	V <sub>SD</sub> *	-	-	1,2	V	I <sub>s</sub> =200mA, V <sub>GS</sub> =0V
*Pulsed		30				
40	•					



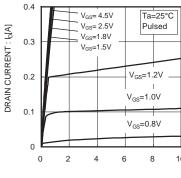
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#### •Electrical characteristic curves



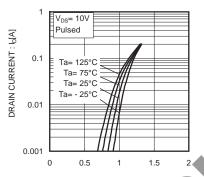
DRAIN-SOURCE VOLTAGE : VDS[V]

Fig.1 Typical Output Characteristics( I )



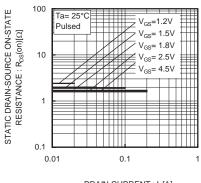
DRAIN-SOURCE VOLTAGE: VDS[V]

Fig.2 Typical Output Characteristics(II)



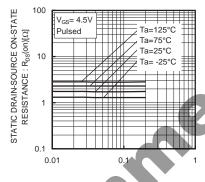
GATE-SOURCE VOLTAGE : VGS[V]

Fig.3 Typical Transfer Charac



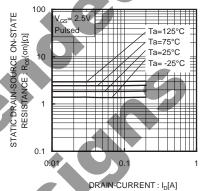
 $\mathsf{DRAIN}\text{-}\mathsf{CURRENT}:\mathsf{I}_\mathsf{D}\![\mathsf{A}]$ 

Fig.4 Static Drain-Source On-State Resistance vs. Drain Current( I )

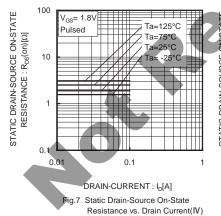


DRAIN-CURRENT : I<sub>D</sub>[A]

Static Drain-Source On-State Resistance vs. Drain Current(II)



.6 Static Drain-Source On-State Resistance vs. Drain Current(III)



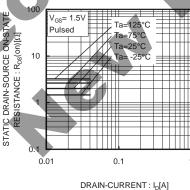


Fig.8 Static Drain-Source On-State Resistance vs. Drain Current(V)

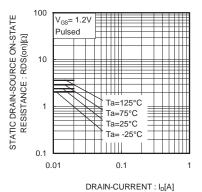
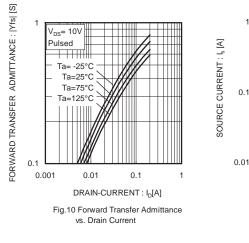
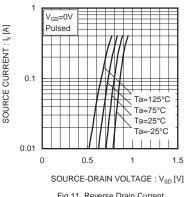


Fig.9 Static Drain-Source On-State Resistance vs. Drain Current(VI) **RUE002N05 Data Sheet** 

STATIC DRAIN-SOURCE ON-STATE





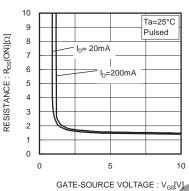
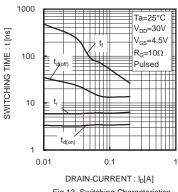


Fig.11 Reverse Drain Current vs. Sourse-Drain Voltage

Fig.12 Static Drain-Source On-State



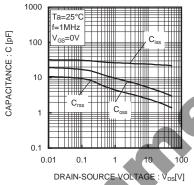


Fig.13 Switching Characteristics

Fig.14 Typical Capacitance
vs. Drain-Source Voltage

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#### Measurement circuits

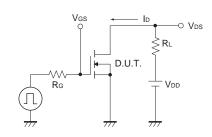


Fig.1-1 Switching time measurement circuit

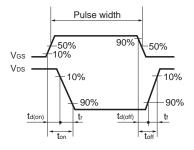


Fig.1-2 Switching waveforms

#### ●Notice

This product might cause chip aging and breakdown under the large electrified environment. Please consider to design ESD protection circuit.



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